

# SURFBOARDS<sup>®</sup>

THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT**™



## 33000 SERIES APPLICATION SPECIFIC ADAPTERS

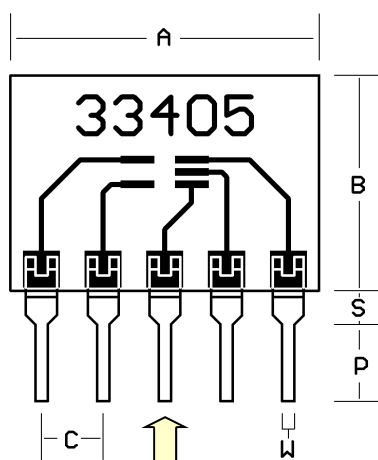
IDS33405

REV A-10-2011

MODEL **33405**

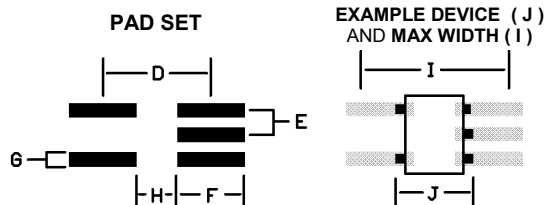
5 LEAD .5 mm PITCH DEVICES

DEVICE LEAD WIDTH 1.5 To Max 3.0 MM



DRAWINGS  
NOT TO  
SCALE

**SINGLE-IN-LINE (SIP) PINS  
ON .100 in. CENTERS**



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING.

[SEE WEBSITE FOR SOLDERING SUGGESTIONS](#)

### BOARD SPECIFICATIONS

**BOARD MATERIAL:** .8mm,  $\pm .13$ mm .031in $\pm .005$  in. Thick G-10 FR-4 Glass Epoxy or equivalent.

**CIRCUITS:** 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board  $\pm .5$ mm .020in.



ACCEPTS **SOT-553 SOT-665**

*PARTIAL LISTING*

- KEC **TE5V**
- PANASONIC **SSMini5-F2, SSMini5-F3  
SSMini5-DA**
- RENESAS **5 Pin XSOF, P-USON-5  
VSON-5**
- ROHM **EMD5, EMT5**
- TEXAS INST. **DRL (R-PDSO-N5)**
- TOSHIBA **E5V**

*ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT*

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers. Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

FIG.	MM	IN.	NOTE:
A	12.7	.500	BOARD WIDTH $\pm .5$ mm .020in.
B	8.89	.350	BOARD HEIGHT $\pm .5$ mm .020in.
C	2.54	.100	SIP PIN SPACE $\pm .20$ mm .008in.
D	2.2	.086	PAD CENTERLINE
E	.5	.020	DEVICE LEAD PITCH
F	1.4	.055	PAD LENGTH
G	.3	.012	PAD WIDTH
H	.8	.031	GAP
I	3.0	.118	MAX LEAD WIDTH
J	1.5	.059	TYPICAL LEAD WIDTH
P	3.3	.130	LENGTH FROM SHOULDER $\pm .5$ mm .020in.
S	1.57	.062	PIN SHOULDER HEGHT
W	.5	.020	PIN WIDTH

**TOLERANCES:** If not noted are  $\pm 20\%$ . Nominal values are given. Controlling unit is Millimeters. Slight Variations due to manufacturing process can occur.

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